

TLC5602C, TLC5602M VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

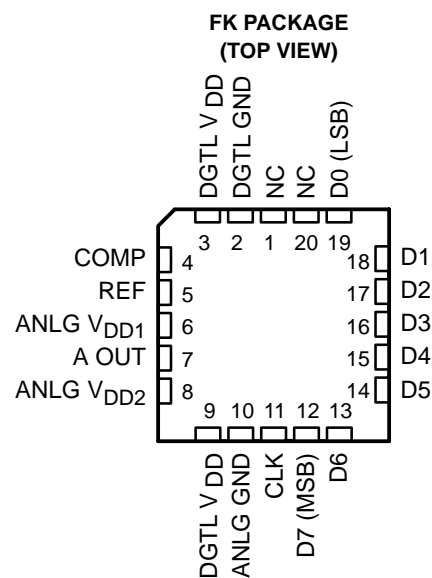
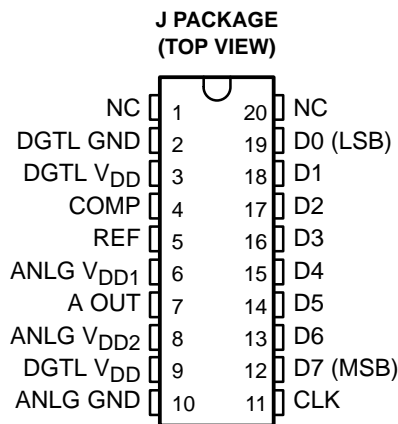
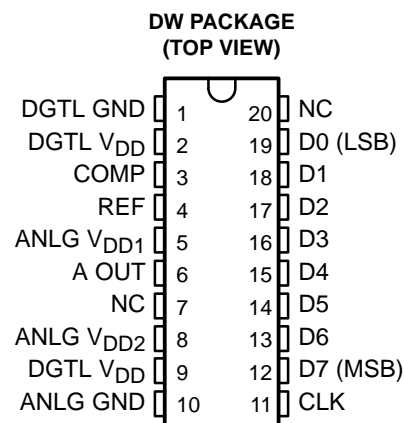
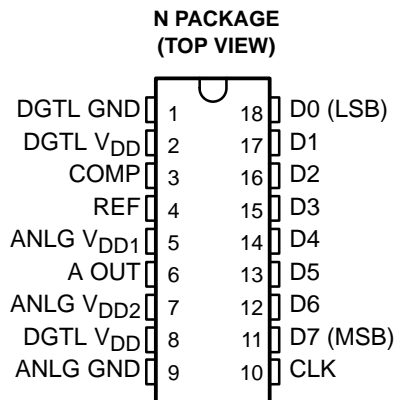
SLAS023D – FEBRUARY 1989 – REVISED JANUARY 2002

- 8-Bit Resolution
- $\pm 0.2\%$ Linearity
- Maximum Conversion Rate
30 MHz Typ
20 MHz Min
- Analog Output Voltage Range
 V_{DD} to $V_{DD} - 1$ V
- TTL Digital Input Voltage
- 5-V Single Power-Supply Operation
- Low Power Consumption . . . 80 mW Typ
- Interchangeable With Fujitsu MB40778

description

The TLC5602x devices are low-power, ultra-high-speed video, digital-to-analog converters that use the LinEPIC™ 1- μ m CMOS process. The TLC5602x converts digital signals to analog signals at a sampling rate of dc to 20 MHz. Because of high-speed operation, the TLC5602x devices are suitable for digital video applications such as digital television, video processing with a computer, and radar-signal processing.

The TLC5602C is characterized for operation from 0°C to 70°C. The TLC5602M is characterized over the full military temperature range of -55°C to 125°C.



NC—No internal connection

LinEPIC is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2002, Texas Instruments Incorporated

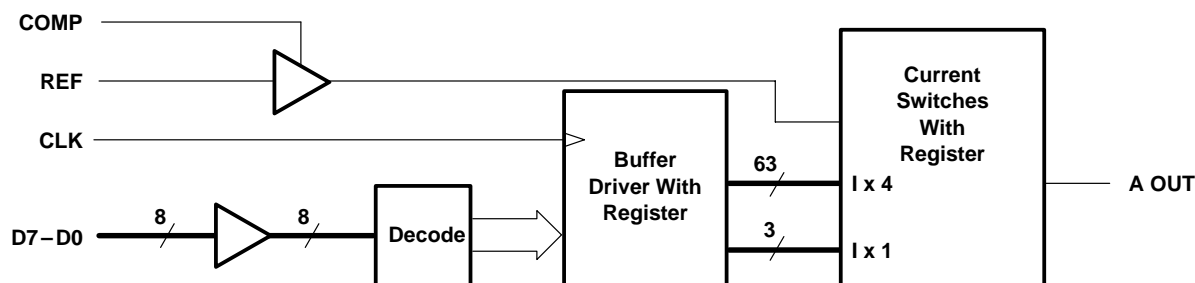
TLC5602C, TLC5602M VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS023D – FEBRUARY 1989 – REVISED JANUARY 2002

AVAILABLE OPTIONS

PACKAGE				
T _A	WIDE-BODY SMALL OUTLINE (DW)	CERAMIC CHIP CARRIER (FK)	CERAMIC DIP (J)	PLASTIC DIP (N)
0°C to 70°C	TLC5602CDW			TLC5602CN
-55°C to 125°C		TLC5602MFK	TLC5602MJ	

functional block diagram



FUNCTION TABLE

STEP	DIGITAL INPUTS								OUTPUT VOLTAGE†
	D7	D6	D5	D4	D3	D2	D1	D0	
0	L	L	L	L	L	L	L	L	3.980 V
1	L	L	L	L	L	L	L	H	3.984 V
127	L	H	H	H	H	H	H	H	4.488 V
128	H	L	L	L	L	L	L	L	4.492 V
129	H	L	L	L	L	L	L	H	4.496 V
254	H	H	H	H	H	H	H	L	4.996 V
255	H	H	H	H	H	H	H	H	5.000 V

† V_{DD} = 5 V and V_{ref} = 4.02 V

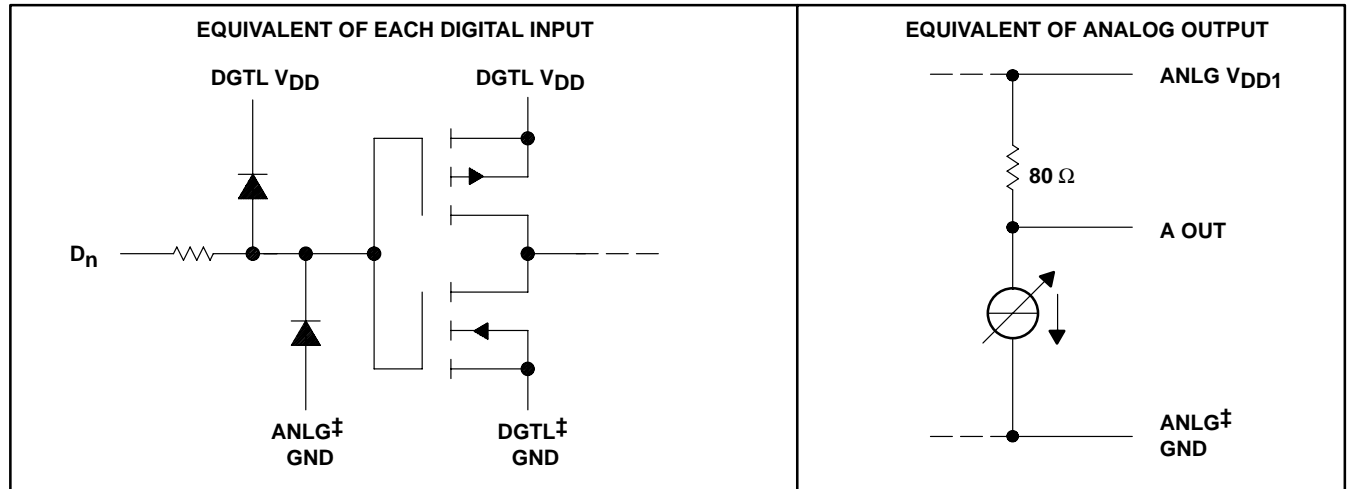


POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

TLC5602C, TLC5602M VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS023D – FEBRUARY 1989 – REVISED JANUARY 2002

schematics of equivalent input and output



† ANLG GND and DGTL GND do not connect internally and should be tied together as close to the device terminals as possible.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, ANLG V_{DD} , DGTL V_{DD}	–0.5 V to 7 V
Digital input voltage range, V_I	–0.5 V to 7 V
Analog reference voltage range, V_{ref}	$V_{DD} - 1.7$ V to $V_{DD} + 0.5$ V
Operating free-air temperature range, T_A : TLC5602C	0°C to 70°C
TLC5602M	–55°C to 125°C
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}	4.75	5	5.25	V
Analog reference voltage, V_{ref}	3.8	4	4.2	V
High-level input voltage, V_{IH}	2			V
Low-level input voltage, V_{IL}			0.8	V
Pulse duration, CLK high or low, t_W	25			ns
Setup time, data before CLK↑, t_{su}	16.5			ns
Hold time, data after CLK↑, t_h	12.5			ns
Phase compensation capacitance, C_{comp} (see Note 1)	1			μF
Load resistance, R_L	75			Ω
Operating free-air temperature, T_A	TLC5602C	0	70	°C
	TLC5602M	–55	125	

NOTE 1: The phase compensation capacitor should be connected between COMP and ANLG GND.

TLC5602C, TLC5602M VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS023D – FEBRUARY 1989 – REVISED JANUARY 2002

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT	
I _{IH}	High-level input current	Digital inputs V _I = 5 V			±1	μA	
I _{IL}	Low-level input current	V _I = 0 V			±1	μA	
I _{ref}	Input reference current	V _{ref} = 4 V			10	μA	
V _{FS}	Full-scale analog output voltage	V _{DD} = 5 V, V _{ref} = 4.02 V	V _{DD} - 15	V _{DD}	V _{DD} + 15	mV	
V _{ZS}	Zero-scale analog output voltage	V _{DD} = 5 V, T _A = full range [§] V _{ref} = 4.02 V,	TLC5602C	3.919	3.98	4.042	V
			TLC5602M	3.919	3.98	4.042	
			TLC5602M	3.919	3.98	4.062	
r _o	Output resistance	T _A = 25°C	TLC5602C	60	80	120	Ω
		T _A = full range [§]					
C _i	Input capacitance	f _{clock} = 1 MHz, T _A = 25°C		15		pF	
I _{DD}	Supply current	f _{clock} = 20 MHz, V _{ref} = V _{DD} - 0.95 V		16	25	mA	

[‡] All typical values are at V_{DD} = 5 V and T_A = 25°C.

[§] Full range for the TLC5602C is 0°C to 70°C, and full range for the TLC5602M is -55°C to 125°C.

operating characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
E _{L(adj)}	Linearity error, best-straight-line	T _A = full range [‡]	TLC5602C		±0.2%	
		T _A = 25°C	TLC5602M		±0.2%	
		T _A = full range [‡]	TLC5602M		±0.4%	
E _L	Linearity error, end point			±0.15%		
E _D	Linearity error, differential			±0.2%		
G _{diff}	Differential gain	NTSC 40-IRE modulated ramp,		0.7%		
f _{diff}	Differential phase	f _{clock} = 14.3 MHz, Z _L ≥ 75 kΩ		0.4°		
t _{pd}	Propagation delay time, CLK to analog output	C _L = 10 pF		25		ns
t _s	Settling time to within 1/2 LSB	C _L = 10 pF		30		ns

[†] All typical values are at V_{DD} = 5 V and T_A = 25°C.

[‡] Full range for the TLC5602C is 0°C to 70°C, and full range for the TLC5602M is -55°C to 125°C.



PARAMETER MEASUREMENT INFORMATION

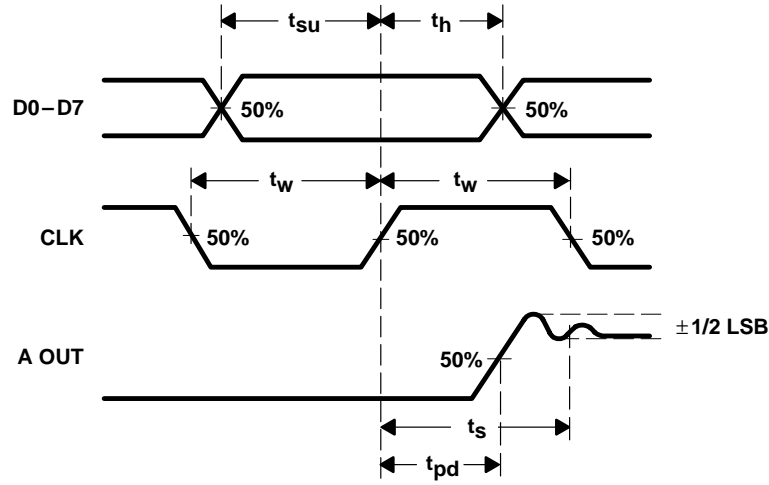


Figure 1. Voltage Waveforms

TLC5602C, TLC5602M VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS023D – FEBRUARY 1989 – REVISED JANUARY 2002

TYPICAL CHARACTERISTICS

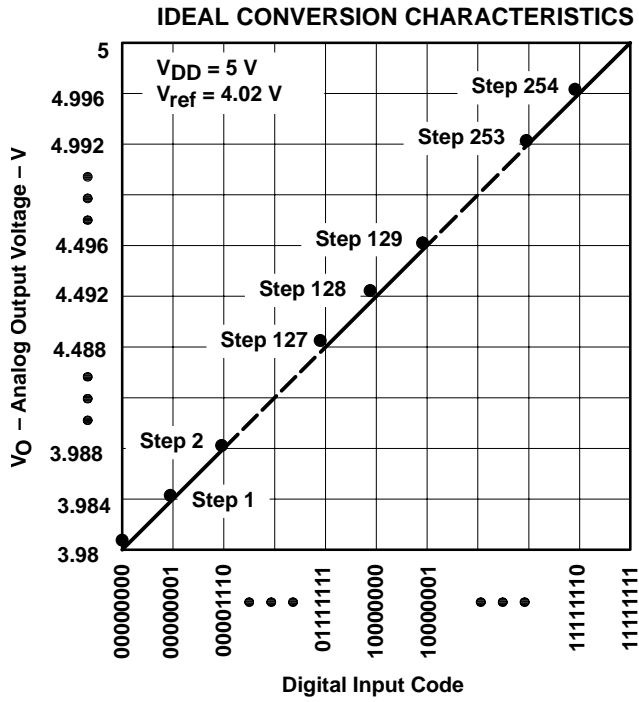


Figure 2

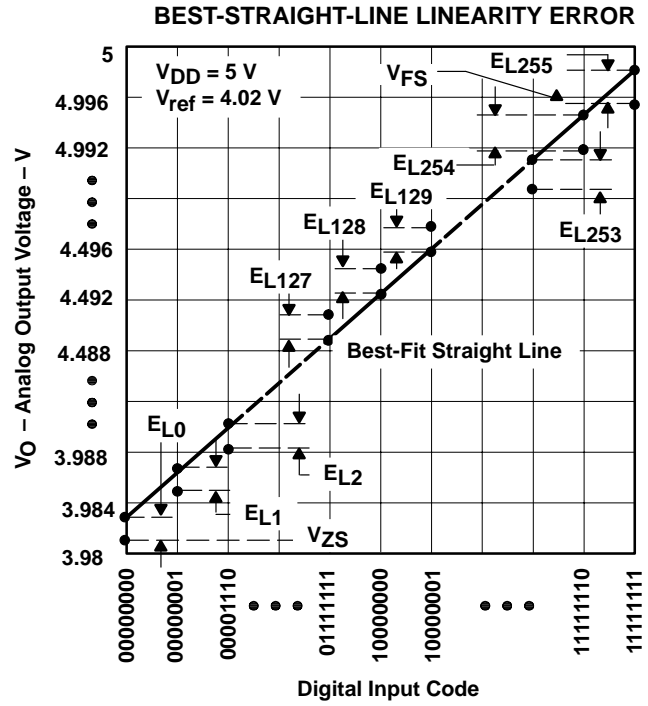


Figure 3

ZERO-SCALE OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

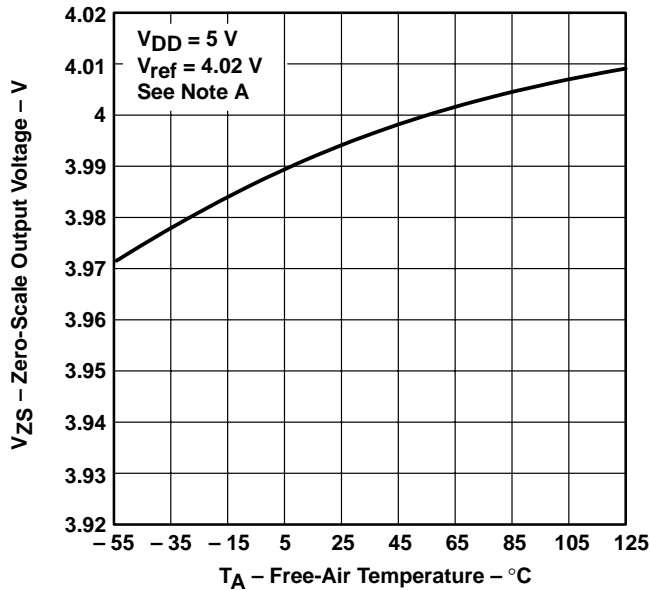


Figure 4

OUTPUT RESISTANCE vs FREE-AIR TEMPERATURE

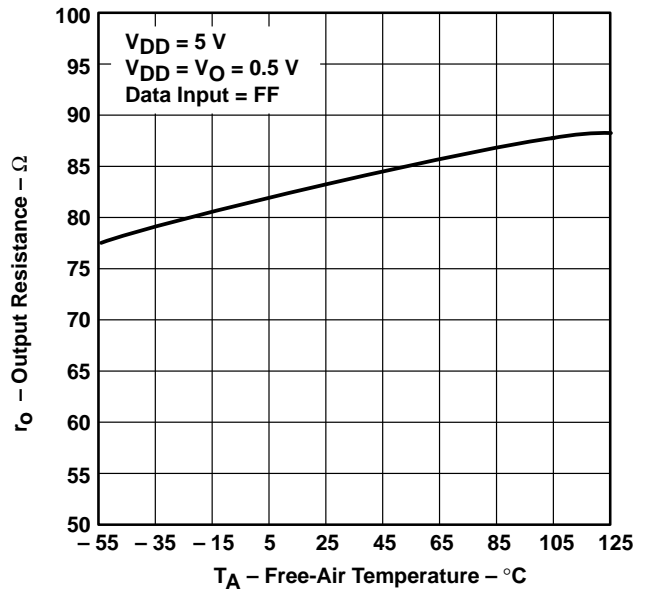


Figure 5

NOTE A: V_{ref} is relative to ANLG GND. V_{DD} is the voltage between ANLG V_{DD} and DGTL V_{DD} tied together and ANLG GND and DGTL GND tied together.



TYPICAL CHARACTERISTICS

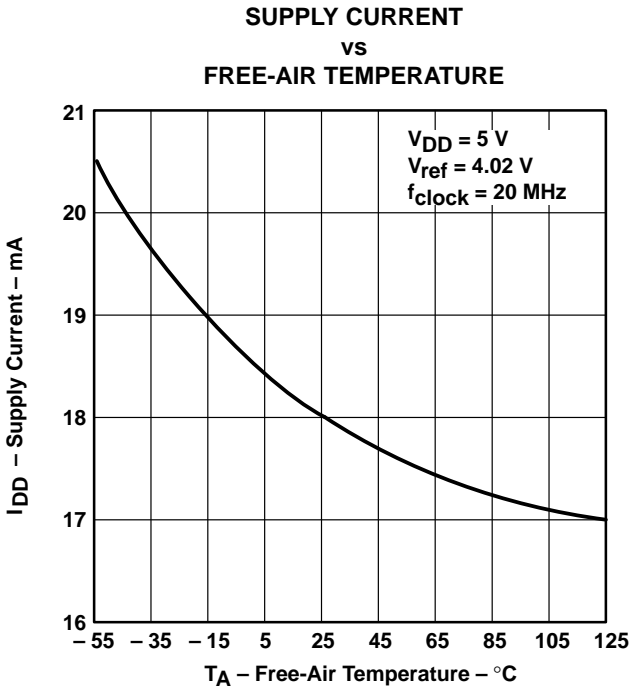
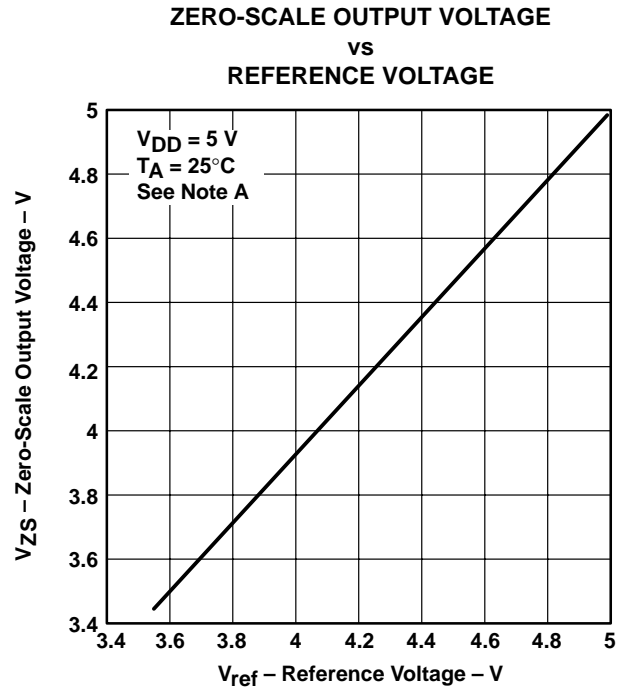


Figure 6



NOTE A: V_{ref} is relative to ANLG GND. V_{DD} is the voltage between ANLG V_{DD} and DGTL V_{DD} tied together and ANLG GND and DGTL GND tied together.

Figure 7

TLC5602C, TLC5602M

VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS023D – FEBRUARY 1989 – REVISED JANUARY 2002

APPLICATION INFORMATION

The following design recommendations benefit the TLC5602 user:

- Physically separate and shield external analog and digital circuitry as much as possible to reduce system noise.
- Use RF breadboarding or RF printed-circuit-board (PCB) techniques throughout the evaluation and production process.
- Since ANLG GND and DGTL GND are not connected internally, these terminals need to be connected externally. With breadboards, these ground lines should connect to the power-supply ground through separate leads with proper supply bypassing. A good method is to use a separate twisted pair for the analog and digital supply lines to minimize noise pickup.

Use wide ground leads or a ground plane on the PCB layouts to minimize parasitic inductance and resistance. The ground plane is the better choice for noise reduction.

- ANLG V_{DD} and DGTL V_{DD} are also separated internally, so they must connect externally. These external PCB leads should also be made as wide as possible. Place a ferrite bead or equivalent inductance in series with ANLG V_{DD} and the decoupling capacitor as close to the device terminals as possible before the ANLG V_{DD} and DGTL V_{DD} leads are connected together on the board.
- Decouple ANLG V_{DD} to ANLG GND and DGTL V_{DD} to DGTL GND with a 1- μ F and 0.01- μ F capacitor, respectively, as close as possible to the appropriate device terminals. A ceramic chip capacitor is recommended for the 0.01- μ F capacitor.
- Connect the phase compensation capacitor between COMP and ANLG GND with as short a lead-in as possible.
- The no-connection (NC) terminals on the small-outline package should be connected to ANLG GND.
- Shield ANLG V_{DD} , ANLG GND, and A OUT from the high-frequency terminals CLK and D7–D0. Place ANLG GND traces on both sides of the A OUT trace on the PCB.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC5602CDW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC5602C	Samples
TLC5602CDWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC5602C	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

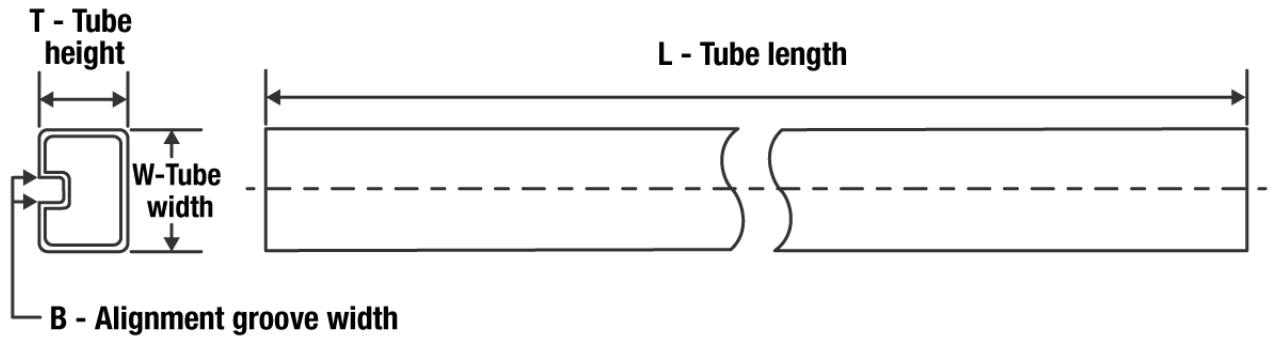

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC5602CDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC5602CDWR	SOIC	DW	20	2000	535.4	167.6	48.3

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TLC5602CDW	DW	SOIC	20	25	506.98	12.7	4826	6.6

DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

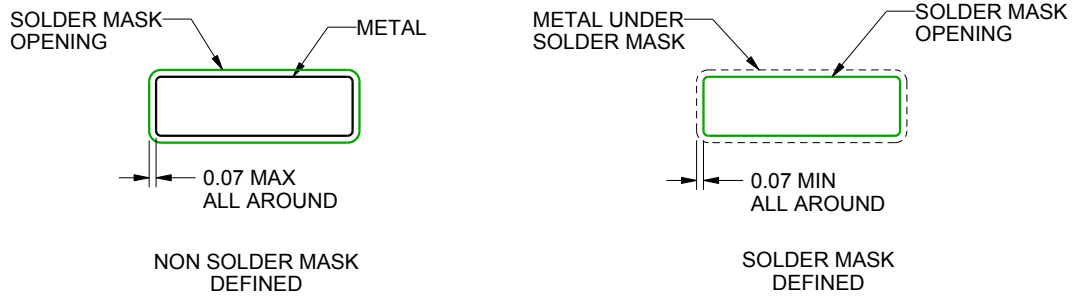
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2022, Texas Instruments Incorporated